



# PRELIMINARY DATA SHEET

## Witcom PA6-2012/079, based on Polyamide 6 (PA6)

reinforced, thermally & electrically conductive, flame retardant modified, free from halogens

Properties	Test methods	Units	PA6-2012/079
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### Physical properties

Specific gravity	ISO 1183	g/cm <sup>3</sup>	1,57
Water absorption at saturation, 23 °C	ISO 62	%	3,5
Humidity absorption, 23 °C/50 % r.h.	ISO 62	%	1,2
Mould shrinkage (flow direction, 3 mm)	ISO 2577	%	0,1 - 0,2

### Mechanical properties

Tensile strength (max.)	ISO 527	MPa	95
Elongation at break	ISO 527	%	1 - 2
Flexural strength	ISO 178	MPa	155
Flexural modulus	ISO 178	GPa	31,0
IZOD impact strength, notched	ISO 180/1eA	kJ/m <sup>2</sup>	4,5
IZOD impact strength, unnotched	ISO 180/1eU	kJ/m <sup>2</sup>	15

### Thermal properties

Heat distortion temperature (1,81 MPa)	ISO 75	°C	205
Relative temperature index, 3 mm, with impact	UL 746B	°C	95
Coefficient of linear thermal expansion	ISO 11359	K-1·10 <sup>-5</sup>	-
Thermal conductivity, in plane	ISO 22007-2	W/mK	21,3

### Flammability

Burning behaviour	ISO 1210	-	V1 @ 1,6mm
UL recognition	UL94	-	-

### Electrical properties

Surface resistivity	ASTM D257	Ω/sq	10 <sup>4</sup> - 10 <sup>6</sup>
Glow wire rating, 1,6 mm	IEC 695-2-1	°C	960

### Processing conditions (injection moulding)

Drying conditions (dehumidifying drier)	: 3 - 5 Hours @ 80 °C
Maximum allowable moisture content	: 0,10 %
Melt temperature	: 250 - 270 °C
Mould temperature	: 60 - 95 °C
Screw speed	: 0,1 - 0,2 m/s
Back pressure	: 0 - 1,0 MPa
Injection pressure	: Keep to a minimum
Injection speed	: Fast ram speed
Hold pressure	: Keep to a minimum

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